

SOT619-22

plastic, thermally enhanced very thin quad flat non-leaded package; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 0.9 mm body

8 February 2019

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN48
Package type industry code	HVQFN48
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	12-01-2016
Manufacturer package code	98ASA00466D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	7	-	mm
package width	-	7	-	mm
seated height	0.8	0.9	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	48	-	



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2 Package outline

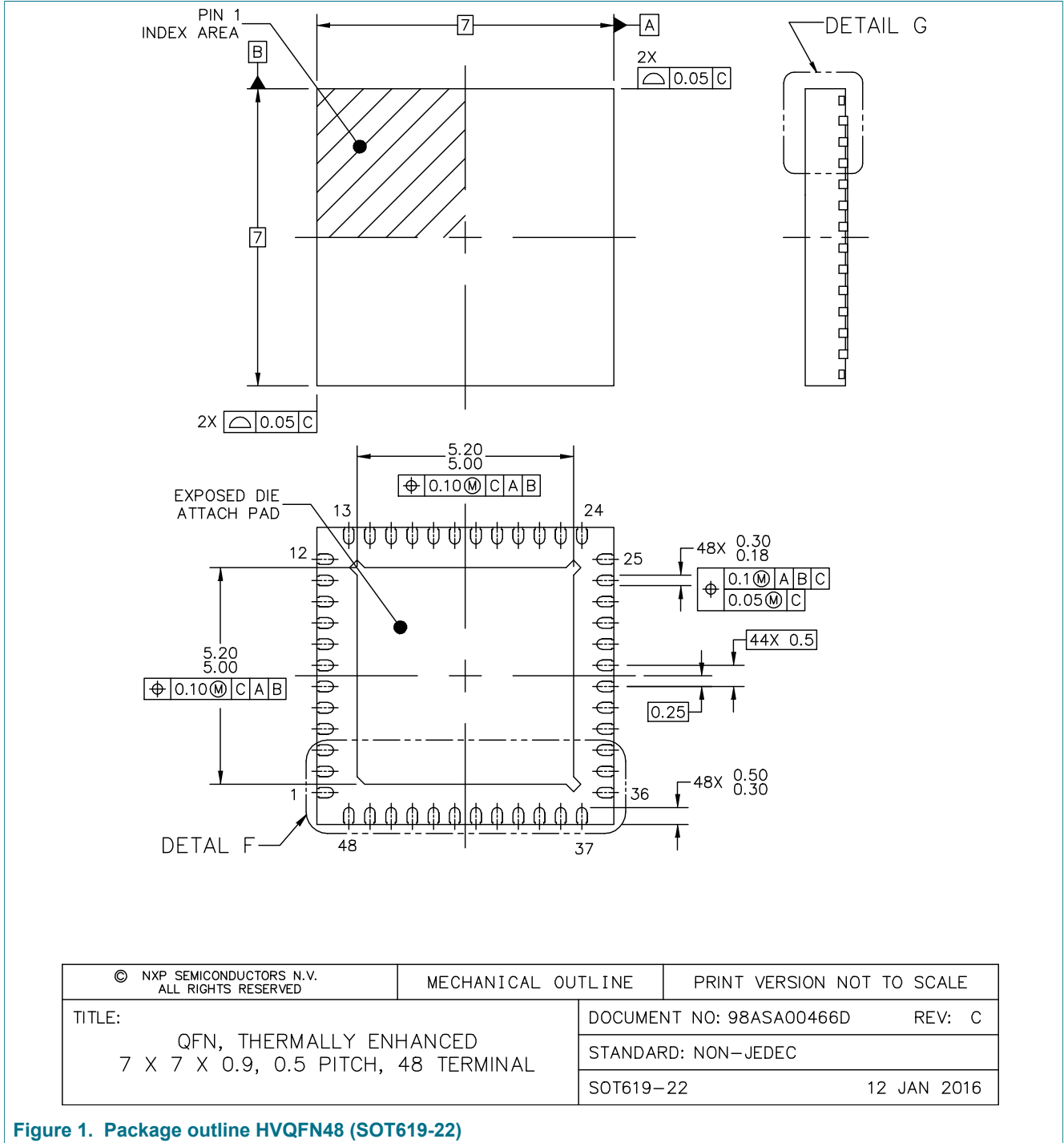


Figure 1. Package outline HVQFN48 (SOT619-22)

plastic, thermally enhanced very thin quad flat non-leaded package; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 0.9 mm body

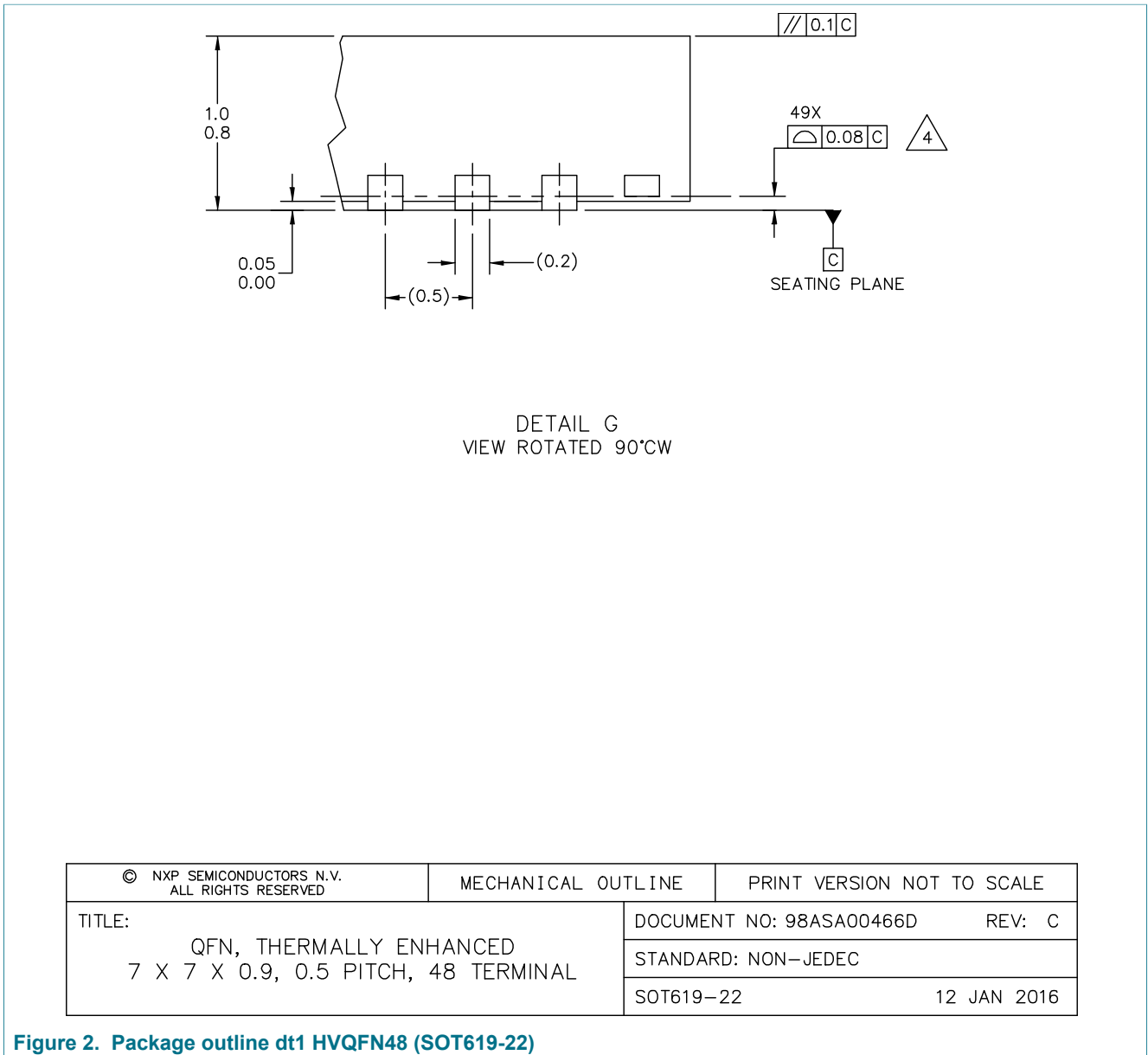


Figure 2. Package outline dt1 HVQFN48 (SOT619-22)

plastic, thermally enhanced very thin quad flat non-leaded package; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 0.9 mm body

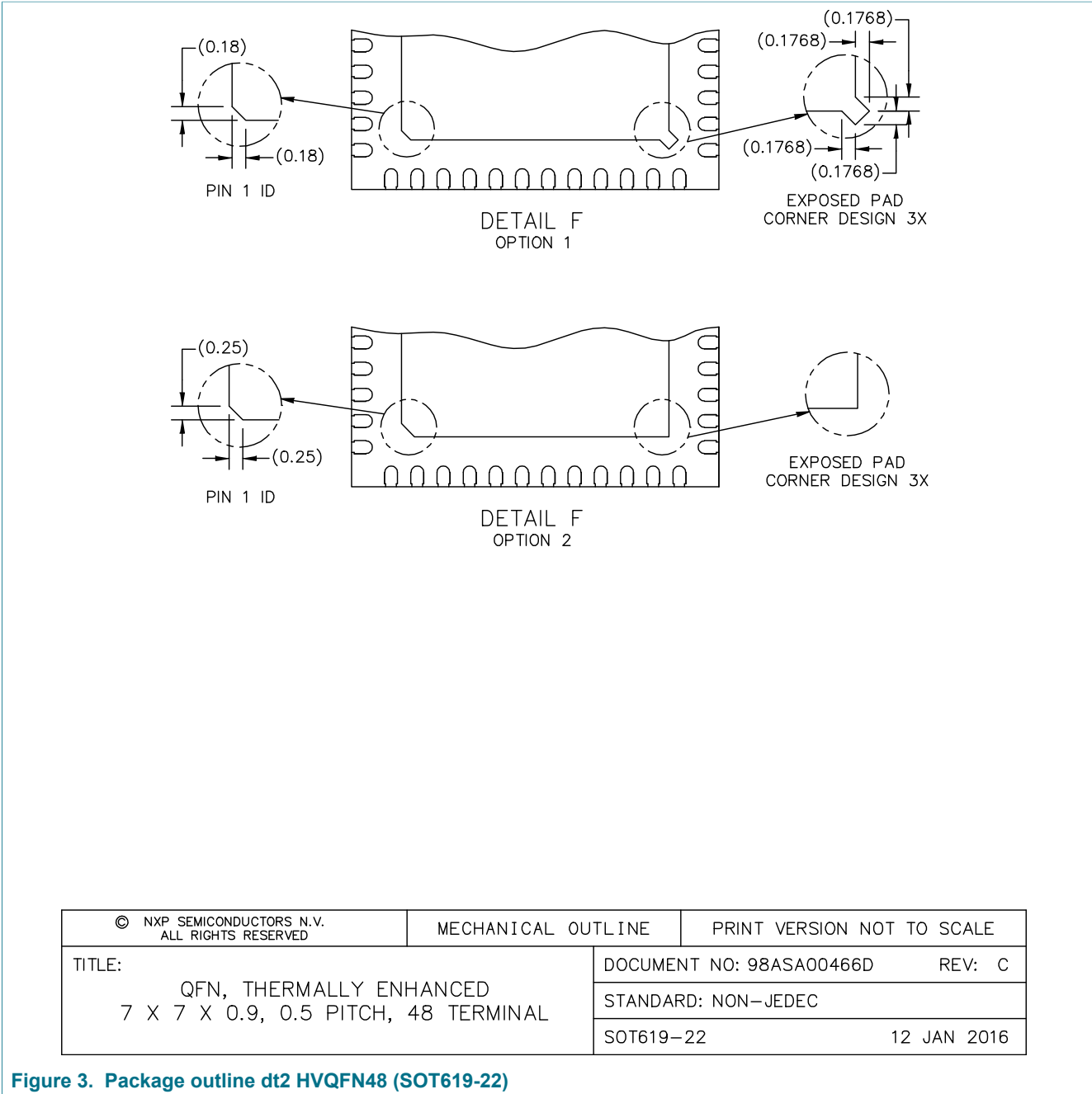



Figure 3. Package outline dt2 HVQFN48 (SOT619-22)

plastic, thermally enhanced very thin quad flat non-leaded package; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 0.9 mm body

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THIS IS A NON-JEDEC REGISTERED PACKAGE.
4.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

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TITLE: QFN, THERMALLY ENHANCED 7 X 7 X 0.9, 0.5 PITCH, 48 TERMINAL		DOCUMENT NO: 98ASA00466D	REV: C
		STANDARD: NON-JEDEC	
		SOT619-22	12 JAN 2016

Figure 4. Package outline note HVQFN48 (SOT619-22)

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3 Legal information

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